

DESCRIPTION

ILLUMINATION OPTICAL SYSTEM, EXPOSURE APPARATUS, AND DEVICE MANUFACTURING METHOD

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TECHNICAL FIELD

The present invention relates to an illumination optical system for use in an exposure apparatus that manufactures a device, such as a semiconductor device, a liquid crystal display device, an imaging device, and a thin-film magnetic head, in a photolithography process, an exposure apparatus including such an illumination optical system, and a method for manufacturing a device with such an exposure apparatus.

BACKGROUND ART

In recent years, the integration of patterns that are formed on a mask has become higher. Thus, to accurately transfer a fine pattern onto a wafer, a mask pattern must be illuminated with the optimal illuminance distribution. Accordingly, a technique that has drawn attention performs modified illumination at a pupil position of an illumination optical system for an exposure apparatus to form an annular-shaped or multipole-shaped (e.g., quadrupole) light intensity distribution and varies the light intensity distribution on a secondary light source, which is formed on a rear focal plane of a micro-fly's eye lens. This technique increases the focal depth and resolution of a projection optical system.

To transform light from a light source to light having

an annular-shaped or multipole-shaped light intensity distribution at a pupil position, for example, Japanese Laid-Out Patent Publication No. 2002-353105 discloses an exposure apparatus including a movable multi-mirror (e.g.,
5 digital micromirror device (DMD), which includes many microscopic elements mirrors that are arranged in an array. The inclination angle and inclination direction of each of the element mirrors are varied to form a predetermined light intensity distribution at a pupil position of the
10 illumination optical system or a position conjugated with the pupil position (secondary light source position formed at a rear focal plane of a micro-fly's eye lens). In this exposure apparatus, light entering each mirror element is reflected by a reflection surface of the mirror element,
15 deflected by a predetermined angle in a predetermined direction, and transformed to light having a predetermined light intensity distribution at the pupil position of the illumination optical system. Exposure is performed by setting the inclination angle and inclination direction of
20 each mirror element in the movable multi-mirror so that a secondary light source image formed on a rear focal plane of the micro-fly's eye lens has the optimal light intensity distribution that corresponds to the pattern or the like of the mask during exposure.

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DISCLOSURE OF THE INVENTION

In the above-described exposure apparatus, a laser light source is used as the light source. However, the light
30 intensity is not uniform in the cross-section of the laser light emitted from the laser light source. Accordingly, when using such laser light to form an annular-shaped or multipole shaped light intensity distribution at the pupil

position of the illumination optical system, non-uniformity of light intensity occurs in a light distribution shape (cross-section of light beam).

5 It is an object of the present invention to provide an illumination optical system, an exposure apparatus including such an illumination optical system, and a method for manufacturing a device with such an exposure apparatus that easily forms the desired light intensity distribution with
10 uniform illumination at the pupil position of the illumination optical system or a position conjugated with the pupil position even when non-uniformity occurs in the cross-section of the light.

15 The structure of an embodiment of the present invention will now be discussed using reference characters. However, the present invention is not limited to this embodiment.

20 An illumination optical system according to one embodiment of the present invention illuminates an irradiated plane (M) with illumination light provided from a light source (1). The illumination optical system includes a spatial light modulator (S1) which is arranged in an optical
25 path of the illumination optical system and cooperates with part of the illumination optical system to form a desired light intensity distribution at a pupil position of the illumination optical system or a position optically conjugated with the pupil position. A detection unit (30 to
30 33) including a light receiving surface (32a, 33a) receiving some of the illumination light detects the light intensity distribution of the illumination light at a position in an optical path extending from the light source to the spatial

light modulator. A control unit (20) controls the spatial light modulator based on the light intensity distribution detected by the detection unit.

5 An exposure apparatus according to one embodiment of the present invention transfers a predetermined pattern onto a photosensitive substrate (W). The exposure apparatus includes the illumination optical system according to the present invention which illuminates the pattern that is
10 arranged on an irradiated plane.

 A method for manufacturing a device according to one embodiment of the present invention exposes a predetermined pattern onto a photosensitive substrate using the exposure
15 apparatus according to the present invention (S44), develops the photosensitive substrate onto which the pattern has been transferred to form a mask layer shaped in correspondence with the pattern on a surface of the photosensitive
20 substrate (S46), and processes the surface of the photosensitive substrate through the mask layer (S48).

 The exposure apparatus according to one embodiment of the present invention includes a detection unit which detects the light intensity distribution of the illumination
25 light at a position in an optical path extending from the light source to the spatial light modulator. Thus, based on the detection result, the spatial light modulator can be controlled to form the desired light intensity distribution at the pupil position of the illumination optical system or
30 a position optically conjugated with the pupil position.

 Further, the exposure apparatus according to one embodiment of the present invention illuminates a mask using

an illumination optical system according to the present invention. Thus, the pattern of a mask can be exposed onto a photosensitive substrate with a high resolution and high throughput.

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The method for manufacturing a device according to one embodiment of the present invention performs exposure with an exposure apparatus including an illumination optical system according to the present invention. Thus, devices can
10 be manufactured with a high resolution and high throughput.

BRIEF DESCRIPTION OF THE DRAWINGS

Fig. 1 is a schematic diagram showing an exposure
15 apparatus according to an embodiment;

Fig. 2 is a diagram showing the structure of a spatial light modulation unit in the embodiment;

Fig. 3 is a diagram showing the structure of a spatial light modulator in the spatial light modulation unit of the
20 embodiment;

Fig. 4 is a schematic diagram showing the structure of a conical axicon system in an illumination optical system according to the embodiment;

Fig. 5 is a diagram illustrating the operation of the
25 conical axicon system with respect to a secondary light source formed through annular illumination according to the embodiment;

Fig. 6 is a schematic diagram showing a first cylindrical lens pair and a second cylindrical lens pair in
30 the illumination optical system according to the embodiment;

Fig. 7 is a diagram illustrating the operation of a zoom lens with respect to a secondary light source formed through the annular illumination according to the

embodiment;

Fig. 8 is a diagram showing the structure of a further illumination optical system according to the embodiment;

Fig. 9 is a flowchart illustrating a method for manufacturing a semiconductor device, which serves as a micro-device, according to the embodiment; and

Fig. 10 is a flowchart illustrating a method for manufacturing a liquid crystal display device, which serves as a micro-device, according to the embodiment.

BEST MODE FOR CARRYING OUT THE INVENTION

An exposure apparatus according to an embodiment of the present invention will now be discussed with reference to the drawings. Fig. 1 is a schematic diagram showing the structure of an exposure apparatus according to the embodiment. In the description hereafter, an XYZ orthogonal coordinate system is set as shown in Fig. 1, and the positional relationship of each member will be described with reference to the XYZ orthogonal coordinate system. The XYZ orthogonal coordinate system is set so that the X axis and the Y axis are parallel to a wafer W, and the Z axis is orthogonal to the wafer W.

With reference to Fig. 1, exposure light (illumination light) is supplied from a laser light source 1 to the exposure apparatus of the present embodiment. The laser light source 1 may be, for example, an ArF excimer laser light source, which generates light having a wavelength of 193 nm, or a KrF excimer laser light source, which generates light having a wavelength of 248 nm. The laser light source 1 emits generally parallel light in the Z direction. The light, which has a rectangular cross-section that is

elongated in the X direction, enters a beam expander 2, which is formed by a pair of lenses 2a and 2b. The lenses 2a and 2b respectively have a negative refractive power and a positive refractive power in a YZ plane as viewed in Fig. 1.

5 Accordingly, the light that enters the beam expander 2 is magnified on a YZ plane as viewed in Fig. 1 and shaped into light having a predetermined rectangular cross-section. The parallel light that has passed through the beam expander 2, which serves as a shaping optical system, enters a beam
10 splitter 3.

The light that has passed through the beam splitter 3 enters a detection unit, which includes a beam splitter 30, a lens 31, a first CCD imaging unit 32, and a second imaging
15 unit 33. In the detection unit (30 to 33), the lens 31 converges the parallel light that has passed through the beam splitter 30 onto a light receiving surface, or detection surface 32a, of the first CCD imaging unit 32. Further parallel light reflected by the beam splitter 30
20 falls on a light receiving surface, or detection surface 33a, of the second CCD imaging unit 33.

In accordance with the inclination of the parallel light from the beam splitter 30, the lens 31 directs the
25 parallel light to a position on the detection surface 32a of the first CCD imaging unit 32. Thus, by detecting the position at which light converges on the detection surface 32a of the first CCD imaging unit 32, the inclination angle of the parallel light from the beam splitter 30 and,
30 consequently, the inclination angle of the light reflected by the beam splitter 3 and directed toward a spatial light modulator S1, which will be described later, can be determined. The first CCD imaging unit 32 is one example of

an incidence angle detection unit that detects the incidence angle at which illumination light enters the spatial light modulator.

5 The illuminance distribution in a cross-section of the light that has passed through the beam splitter 30 is detected with the detection surface 33a of the second CCD imaging unit 33. By obtaining the center of the illuminance distribution, displacement of the parallel light from the
10 beam splitter 30 and consequently, displacement of the light reflected by the beam splitter 3 and directed to the spatial light modulator S1 can be obtained.

 The first and second CCD imaging units 32 and 33 can
15 receive a plurality of light pulses from the light source 1 and can output a detection signal every receiving one or more light pulses.

 To attenuate the illuminance of the light directed
20 toward the first and second CCD imaging units 32 and 33 when necessary, a detachable light attenuation filter formed by a neutral density (ND) filter having a predetermined transmittance may be arranged between the beam splitter 3 and the first and second CCD imaging units 32 and 33.
25 Attachment and detachment of the light attenuation filter and gain adjustment of the first and second CCD imaging units 32 and 33 enable the detection signal level of each CCD imaging unit to be kept within an appropriate range.

30 The detection signals from the first and second CCD imaging units 32 and 33 that include information on light angle deviation and light position deviation are sent to a control unit 20. The light reflected by the beam splitter 3

and deflected in the Y direction enters the spatial light modulation unit SM1.

As shown in Fig. 2, the spatial light modulation unit SM1 includes a prism P1 and a spatial light converter S1, which is integrally attached to the prism P1. The prism P1, which is a rectangular parallelepiped, has a side surface in which a V-shaped, wedge-like notch is formed. That is, the prism P1 has a V-shaped notch formed by two planes PS1 and PS2, which intersect each other at an obtuse angle. The two planes PS1 and PS2 are in contact with a straight line Pla, which extends along the X axis shown in Fig. 2. The spatial light modulator S1 is attached to the prism P1 on a side surface that is opposite the V-shaped notch. Inner sides of the two planes PS1 and PS2 function as first and second reflection surfaces R11 and R12.

The prism P1 is arranged so that the side surface to which the spatial light modulator S1 is attached is parallel to the optical axis AX and so that the first reflection surface R11 is located at the side closer to the beam splitter 3 and the second reflection surface R12 is located at the side closer to an afocal lens, which will be described later. The first reflection surface R11 of the prism P1 reflects incident light in the direction of the spatial light modulator S1 (parallel to the optical axis AX). The spatial light modulator S1, which is arranged in an optical path between the first reflection surface R11 and the second reflection surface R12, reflects the light reflected by the first reflection surface R11 toward the second reflection surface R12. The reflection surface R12 of the prism P1 reflects and emits the light reflected by the spatial light modulator S1 toward the afocal lens 5.

In accordance with the position at which the light reflected by the first reflection surface R11 enters the spatial light modulator S1, the spatial light modulator S1 spatially modulates the light. As shown in Fig. 3, the
5 spatial light modulator S1 includes a two-dimensional array of a plurality of microscopic mirror elements SE1. For example, in the light that enters the spatial light modulator S1, a light ray L1 falls on a mirror element SE1a, which is one of the plurality of mirror elements SE1 of the
10 spatial light converter S1, and a light ray L2 falls on a mirror element SE1b, which is one of the plurality of mirror elements SE1 of the spatial light converter S1 differing from the mirror element SE1a. The mirror elements SE1a and SE1b respectively perform spatial modulation on the light
15 rays L1 and L2 in accordance with their positions.

The prism P1 is arranged so that the air-equivalent length from incident positions IP1 and IP2 at which the light rays L1 and L2 enter the prism P1 to the mirror
20 elements SE1a and SE1b and then to emission positions OP1 and OP2 from which light is emitted is equal to the air-equivalent length from positions corresponding to the incident positions IP1 and IP2 to positions corresponding to the emission positions OP1 and OP2 when the optical path of
25 exposure light does not include the prism P1. The air-equivalent length is the optical path length when an optical path length in an optical system is converted to air having a refractive index of one. The air-equivalent length of a medium having refractive index n is obtained by multiplying
30 the physical or actual optical path length of the medium by $1/n$.

As shown in Fig. 3(a), the spatial light modulator S1

is a movable multi-mirror including a plurality of mirror elements SE1, which are microscopic reflection elements. Each of the mirror elements SE1 is movable and has a reflection surface. In each mirror element SE1, the orientation of the reflection surface, that is, the inclination angle and inclination direction of the reflection surface is independently driven and controlled by a spatial light modulator (SLM) drive unit 26, which is controlled by a control unit 20. Each mirror element SE1 is continuously rotatable by a desired rotation angle about two rotation axes that extend perpendicular to each other and parallel to the reflection surface. That is, the mirror elements SE1 are each controllable so as to inline two-dimensionally along the reflection surface.

As shown in Fig. 3(b), one example of a drive mechanism for a mirror element SE1 includes a rod member 41, which supports the mirror element SE1 in a manner enabling inclination about two perpendicular axes in the reflection surface, a support substrate 42, which supports the rod member 41, four electrodes 43, which are arranged on the support substrate 42 so as to surround the rod member 41, and four electrodes (not shown), which are arranged on the rear surface of the mirror element SE1 facing toward the four electrodes 43. In this example, the spatial light modulator (SLM) drive unit 26 controls the potential difference between each of the four electrodes 43 and the corresponding electrode on the rear surface of the mirror element SE1 to control the electrostatic force that acts between the electrodes so as to swing and incline mirror element SE1. This continuously controls the inclination angle of the mirror element SE1 about the two perpendicular axes of the reflection surface within a predetermined

variable range. The structure of the spatial light modulator S1 is disclosed, for example, in Japanese Laid-Open Patent Publication No. 2002-353105. The electrodes 43 shown in Fig. 3(b) are arranged at the apexes (corners) of the rectangular mirror element SE1 but may be arranged instead at a position
5 corresponding to each side of the mirror element SE1.

The drive mechanism for the mirror element SE1 is not limited to the structure of the present embodiment and any
10 other mechanism may be used.

Here, the mirror elements SE1 have square outlines and are flat but are not limited in such a manner. However, from the viewpoint of light utilization efficiency, it is
15 preferable that the mirror elements SE1 have outlines enabling an arrangement that eliminates gaps. It is also preferable that the gap between adjacent mirror elements SE1 be minimized. Further, it is preferable that the mirror elements SE1 be as small as possible so that fine changes
20 can be made to the illumination conditions. Moreover, the reflection surfaces of the mirror elements SE1 do not have to be planar surfaces and may be curved surfaces such as concave surfaces and convex surfaces.

25 The spatial light modulator S1 is capable of performing modified illumination, which forms a desired light intensity distribution that is circular, annular, dipole-shaped, quadrupole-shaped, or the like at a pupil position (pupil surface) of an illumination optical system.
30 Specifically, a storage unit 22, which is accessible by the control unit 20, stores information, for example, in the form of a lookup table, on the inclination angle and inclination direction of the mirror elements SE1 in the

spatial light modulator S1 to form a light intensity distribution that is circular, annular, dipole-shaped, quadrupole-shaped, or the like at the pupil position of the illumination optical system when the incident light has no
5 light intensity variations.

When detecting variations (non-uniformity) in the light intensity of the illumination light at a position in the optical path extending from the light source 1 to the
10 spatial light modulator S1 based on the detection result of the detection unit (30 to 33), to form light distributions that are circular, annular, dipole-shaped, quadrupole-shaped, or the like, the control unit 20 performs an optimization calculation to uniform the light distribution
15 and calculates a corrected inclination angle and corrected inclination direction of each mirror element SE1. Based on the corrected inclination angle and inclination direction, the control unit 20 sends a control signal to the SLM drive unit 26, and the SLM drive unit 26 controls the inclination
20 angle and inclination direction of each mirror element SE1 to form the desired light intensity distribution at the pupil position of the illumination optical system or a position optically conjugated with the pupil position.

25 The correction operation will now be discussed in more detail. For each of the plurality of mirror elements SE1 in the spatial light modulator S1 of the spatial light modulation unit SM1, the control unit 20 obtains the intensity of the light entering the mirror element SE1 from
30 the light intensity distribution in the cross-section of the illumination light detected by the detection unit (30 to 33). Then, the control unit 20 calculates the light intensity distribution in the light distribution shape

formed at the pupil position of the illumination optical system using the information stored in the storage unit 22 on the inclination angle and inclination direction of each mirror element SE1 and the information related to the
5 intensity of the light entering each mirror element SE1.

Further, the control unit 20 obtains the corrected inclination angle and corrected inclination direction of each mirror element SE1, for example, through an appropriate
10 minimization process, such as least squares or attenuation least squares using the inclination angle and inclination direction of each mirror element SE1 as a variable and the light intensity distribution in the light intensity distribution shape that is to be formed at a pupil position
15 in the illumination optical system as a target value. The correction operation does not use a Fourier transform that would require time for calculation. Thus, the inclination angle and inclination direction of each mirror element SE1 is quickly calculated.

20

Further, when the light entering the spatial light modulation unit SM1 inclines from a predetermined initial state, displacement of the light distribution shaped formed at the pupil position of the illumination optical system
25 would occur in the pupil plane. Therefore, in the present embodiment, the control unit 20 corrects the inclination angles of the plurality of mirror elements SE1 in the spatial light modulator S1 of the spatial light modulation unit SM1 based on information on angle deviations of the
30 illumination light detected by the detection unit (30 to 33).

Specifically, the control unit 20 uses the information

on the angle deviation of the illumination light detected by the detection unit (30 to 33) to correct the inclination angle and inclination direction of each mirror element SE1 stored in the storage unit 22 in the form of a lookup table.

5 For example, when the angle deviation of the illumination light is θ , the angle deviation becomes 2θ when the light is reflected by each mirror element SE1. The inclination angle of each mirror element SE1 for correcting the angle deviation 2θ of the reflection light is $-\theta$. Thus, the
10 control unit 20 adds the correction angle $-\theta$ to the information on the inclination angle and inclination direction of each mirror element SE1 stored in the form of a lookup table to obtain the corrected inclination angle and corrected inclination direction of each mirror element SE1.
15 This correction operation enables the elimination of an optical axis inclination correction mechanism that would be arranged between the light source and the main body of the exposure apparatus.

20 In the present embodiment, the spatial light modulator S1 is controlled so that the light distribution shape of incident light is transformed from a rectangular shape to an annular shape. The light that passes through the spatial light modulation unit SM1 enters the afocal lens 5 (relay
25 optical system) and forms an annular light intensity distribution near a pupil position of the afocal lens 5 (and consequently the illumination optical system) or near the pupil position. The afocal lens 5 is an afocal system (non-focal optical system) in which its front focal point is
30 located at the same position as the spatial light modulator S1 and its rear focal point is located at the same position as a predetermined plane 6, which is indicated by broken lines in the drawing. Accordingly, the light entering the

spatial light modulator S1 forms an annular light intensity distribution at the pupil position of the afocal lens 5 and is then emitted from the afocal lens 5 as parallel light.

5 In an optical path between a front lens group 5a and rear lens group 5b of the afocal lens 5, a conical axicon system 87, a first cylindrical lens pair 88, and a second cylindrical lens pair 89 are arranged at or near the pupil position of the illumination optical system from the light
10 source side.

 Fig. 4 is a schematic diagram showing the conical axicon system 87, which is arranged at or near the pupil position of the illumination optical system. The conical
15 axicon system 87 includes from the light source side a first prism 87a and a second prism 87b. The first prism 87a includes a concave, conical refraction surface (concave refraction surface). The second prism 87b includes a convex, conical refraction surface (convex refraction surface) that
20 is formed to be complement so as to enable contact with the concave, conical refraction surface of the first prism 87a. The first prism 87a is arranged so that its planar surface faces toward the light source side and its concave, conical refraction surface faces toward a mask M. The second prism
25 87b is arranged so that its convex, conical refraction surface faces toward the light source and its planar surface faces toward the mask M.

 At least either one of the first prism 87a and the
30 second prism 87b is movable along the optical axis AX so that the interval between the concave, conical refraction surface of the first prism 87a and the convex, conical refraction surface of the second prism 87b (hereinafter,

referred to as the interval of the conical axicon system 87) is variable. In a state in which the concave, conical refraction surface of the first prism 87a and the convex, conical refraction surface of the second prism 87b are in contact with each other, the conical axicon system 87 functions as a plane parallel plate and does not affect an annular secondary light source that is formed by a micro-lens array 10, which will be described later. However, when separating the concave, conical refraction surface of the first prism 87a and the convex, conical refraction surface of the second prism 87b, the conical axicon system 87 functions as a so-called beam expander. Accordingly, when varying the interval in the conical axicon system 87, the incident angle of the light entering the predetermined plane 6, which is indicated by the broken line in Fig. 1, is varied.

Fig. 5 includes drawings illustrating the operation of the conical axicon system 87 with respect to a secondary light source formed through annular illumination. Fig. 5(a) is a drawing showing an annular secondary light source 130a that is in the smallest state in which the interval in the conical axicon system 87 is zero and the focal length of a zoom lens 7, which will be described later, is set to a minimum value (hereinafter, referred to as the "standard state"). Fig. 5(b) is a drawing showing an annular secondary light source 130b formed in a state in which the interval in the conical axicon system 87 is increased to a predetermined value (the focal length of the zoom lens 7 is invariable). The width of the secondary light source 130b in the radial direction (a value that is $1/2$ the difference between the outer diameter and inner diameter, indicated by the double-headed arrows in the drawings) is the same as the width of

the secondary light source 130a in the radial direction. When increasing the interval in the conical axicon system 87 from zero to a predetermined value, the outer diameter and inner diameter of the annular secondary light source can be
5 increased from the standard state while maintaining the same radial width of the annular secondary light source as the standard state. That is, the conical axicon system 87 functions to vary the annular ratio (inner diameter / outer diameter) and size (outer diameter) of the secondary light
10 source without changing the radial width of the annular secondary light source.

Fig. 6 is a schematic diagram showing the first cylindrical lens pair 88 and the second cylindrical lens
15 pair 89 arranged in an optical path between the front lens group 5a and rear lens group 5b of the afocal lens 5. As shown in Fig. 6, the first cylindrical lens pair 88 includes from the light source side a first cylindrical negative lens 88a, which has, for example, negative refractive power in a
20 YZ plane and no refractive power in an XY plane, and a first cylindrical positive lens 88b, which has positive refraction power in a YZ plane and no refractive power in an XY plane. The second cylindrical lens pair 89 includes from the light source side a second cylindrical negative lens 89a, which
25 has, for example, negative refractive power in an XY plane and no refractive power in a YZ plane, and a second cylindrical positive lens 89b, which has positive refraction power in an XY plane and no refractive power in a YZ plane.

30 The first cylindrical negative lens 88a and the first cylindrical positive lens 88b are formed so as to rotate integrally about the optical axis AX. In the same manner, the second cylindrical negative lens 89a and the second

cylindrical positive lens 89b are formed so as to rotate integrally about the optical axis AX. The first cylindrical lens pair 88 functions as a beam expander having power in the Z direction, and the second cylindrical lens pair 89
5 functions as a beam expander having power in the X direction. Further, in the present embodiment, the first cylindrical lens pair 88 and the second cylindrical lens pair 89 are set to have the same power. Accordingly, the light that passes through the first cylindrical lens pair 88
10 and the second cylindrical lens pair 89 is subjected to a magnification effect resulting from the same powers in the Z direction and X direction.

The light that passes through the afocal lens 5 enters
15 the zoom lens 7, which varies the σ value. The predetermined plane 6 is located at or near the front focal point of the zoom lens 7, and the micro-lens array 10, which will be described later, is arranged at or near the rear focal plane of the zoom lens 7. Thus, the zoom lens 7 arranges the
20 predetermined plane 6 and the incidence surface of the micro-lens array 10 to substantially satisfy an optical Fourier transform relationship and consequently arranges the pupil position of the afocal lens 5 and the incidence surface of the micro-lens array 10 to be generally
25 conjugated with each other. Accordingly, in the same manner as the pupil position of the afocal lens 5, for example, an annular illumination field is formed about the optical axis AX on the incidence surface of the micro-lens array 10. The entire shape of the annular illumination field varies in
30 similarity in a manner dependent on the focal length of the zoom lens 7. That is, the size of the secondary light source (planar light source) formed at a position optically conjugated to the pupil position of the illumination optical

system by the micro-lens array 10 is varied in similarity in a manner dependent on the focal length of the zoom lens 7 while keeping the amount of the illumination light emitted from the laser light source 1 substantially constant.

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Fig. 7 includes drawings illustrating the operation of the zoom lens 7 with respect to the secondary light source formed by the annular illumination. Fig. 7(a) is a drawing showing the annular secondary light source 130a that is
10 formed in the standard state, and Fig. 7(b) is a drawing showing an annular secondary light source 130c that is formed in a state in which the focal length of the zoom lens 7 is increased to a predetermined value (the interval of the conical axicon system 87 is invariable). Referring to Figs.
15 7(a) and 7(b), when increasing the focal length of the zoom lens 7 from the minimum value to a predetermined value, the annular secondary light source 130a is transformed to the secondary light source 130c by magnifying the entire shape of the annular secondary light source 130a in similarity
20 while keeping the amount of illumination light substantially constant. That is, the zoom lens 7 functions to vary the width and size (outer diameter) of the annular secondary light source without changing the annular ratio of the annular secondary light source. The light that passes
25 through the zoom lens 7 enters a beam splitter 8. The light reflected by the beam splitter 8 enters a CCD imaging unit 9 (detection unit). The CCD imaging unit 9 sends an image signal to the control unit 20. The beam splitter 8, which is arranged in an optical path between the spatial light
30 modulator and irradiated plane, is also referred to as an optical path branching member, which branches off some of the illumination light from the optical path and guides the branched light to an information acquisition unit.

The light that passes through the beam splitter 8 enters the micro-lens array 10, which serves as an optical integrator. The incidence angle of the light entering the micro-lens array 10 varies in accordance with changes in the interval in the conical axicon system 87 in the same manner as the angle of the light entering the predetermined plane 6. The micro-lens array 10 is an optical device formed by a matrix of a plurality of densely arranged micro lenses having positive refractive power. Each micro lens of the micro-lens array 10 includes a rectangular cross-section, which is in similarity with the shape of the illumination field that is to be formed on the mask M (i.e., a plane to be irradiated or an irradiated plane). (consequently, the shape of the exposure region that is to be formed on a wafer W). The light entering the micro-lens array 10 is divided two-dimensionally by the plurality of micro lens so as to form at a rear focal plane (consequently, an illumination pupil) a secondary light source having generally the same light distribution as the illumination field formed by the light entering micro-lens array 10, that is, a secondary light source, which is formed by a substantially annular planar light source extending about the optical axis AX.

Since in the present example the mask M located on an irradiated plane is illuminated by Köhler illumination, the plane on which this secondary light source is formed is a plane conjugate with an aperture stop of the projection optical system PL and can be called an illumination pupil plane of the illumination apparatus IL. Typically, the irradiated plane (the plane on which the mask M is arranged or the surface on which the wafer W is arranged) becomes an optical Fourier transform plane with respect to the illumination pupil plane. The pupil intensity distribution is a light intensity distribution on the illumination pupil

plane of the illumination apparatus IL or on a plane
conjugate with the illumination pupil plane. However, when
the number of wavefront divisions by the micro-lens array 10
is large, an overall luminance distribution formed on the
5 entrance surface of the micro-lens array 10 shows a high
correlation with the overall intensity distribution of the
entire secondary light source (pupil intensity
distribution), and, therefore, the light intensity
distributions on the entrance surface of the micro-lens
10 array 10 and on a plane conjugate with the entrance surface
can also be called pupil intensity distributions. Concerning
such micro-lens array 10, reference can be made to U.S. Pat.
No. 6,913,373, and U.S. Pat. Application No. 2008/0074631.
The micro-lens array 10 can be termed a micro fly's eye
15 lens.

The light from the annular secondary light source
formed on the rear focal plane of the micro-lens array 10
passes through an aperture stop 12, which can be arranged at
20 or near the rear focal plane (emission plane) of the micro-
lens array 10. The aperture stop 12 is formed, for example,
by an iris stop or the like that limits the size of the
secondary light source formed on the rear focal plane of the
micro-lens array 10 to a predetermined size. The light beams
25 that pass through the aperture stop 12 passes through a beam
splitter 14 and a condenser lens 17a and illuminates a mask
blind MB in a superimposed manner. The light reflected by
the beam splitter 14 passes through a lens 15 and enters a
photodiode 16. The photodiode 16 sends a detection signal to
30 the control unit 20. The beam splitter 14, which is arranged
in the optical path between the spatial light modulator and
irradiated plane, is also referred to as an optical path
branching member, which branches off some of the

illumination light from the optical path and guides the branched light to an information acquisition unit.

A rectangular illumination field, which is in
5 accordance with the shape and focal length of each micro lens forming the micro-lens array 10, is formed in the mask blind MB, which serves as an illumination field stop. The light beams that pass through a rectangular aperture of the mask blind MB is subjected to a light converging operation
10 of an imaging optical system 17b and then reflected by a reflection mirror 19 to illuminate in a superimposing manner the mask M, on which a predetermined pattern is formed. That is, the imaging optical system 17b forms an image of the rectangular aperture in the mask blind MB on the mask M,
15 which is placed on a mask stage MS. The laser light source 1 to reflection mirror 19, the CCD imaging units 32 and 33, and the spatial light modulation unit SM1 form an illumination optical system.

20 The light that passes through the pattern on the mask M forms a pattern image of the mask M on the wafer W, which is a photosensitive substrate. In this manner, the pattern of the mask M is sequentially exposed onto each exposure region in the mask by performing batch exposure or scan
25 exposure while two-dimensionally drive-controlling the wafer W on a wafer stage WS in a plane that is orthogonal to the optical axis AX of the projection optical system PL.

In the exposure apparatus of the present embodiment,
30 the control unit 20 detects in predetermined time intervals the light intensity distribution (information related to light intensity distribution) at the pupil position of the illumination optical system or a position optically

conjugated with the pupil position based on the detection signal from the CCD imaging unit 9. When the desired light intensity distribution is not formed at the pupil position of the illumination optical system or when variations (non-uniformity) in the light intensity is detected in the light distribution shape; the control unit 20 corrects the optimization calculation, which is performed by the control unit 20, for the inclination angle and inclination direction of each mirror element SE1 based on the detection results of the CCD imaging units 32 and 33. More specifically, based on the detection results of the CCD imaging units 32 and 33, the control unit 20 performs an optimization calculation so that the light intensity becomes uniform in the light distribution shape on the pupil plane of the illumination optical system. However, as time elapses, changes take place in the optical characteristics of the illumination optical system. This may result in the light intensity becoming non-uniform in the light distribution shape at the pupil position of the illumination optical system. Accordingly, the control unit 20 corrects the optimization calculation based on the detection result of the CCD imaging unit 9. Then, the control unit 20 adjusts the inclination angle and inclination direction of each mirror element SE1 through the corrected optimization calculation based on the detection results of the CCD imaging units 32 and 33. Based on the adjusted inclination angle and inclination direction, the control unit 20 controls the SLM drive unit 26 to control the inclination angle and inclination direction of each mirror element SE1 and form the desired light distribution shape at the pupil position of the illumination optical system or a position optically conjugated with the pupil position.

The exposure apparatus of the present embodiment shown in Fig. 1 is arranged separately from a movable exposure stage (wafer stage WS), which holds a processed substrate such as the wafer W. A CCD imaging unit 39 (detection unit) is arranged on a measurement stage, which supports various measurement members and sensors. Based on light that passes through both of the illumination optical system and the projection optical system, the CCD imaging unit 39 detects the light intensity distribution at the pupil position of the illumination optical system (projection optical system) and a position optically conjugated with the pupil position and sends the detection result to the control unit 20. The employment of the CCD imaging unit 39 enables correction of influences resulting from optical characteristic variations that occur as time elapses in the projection optical system in addition to the illumination optical system. Such a CCD imaging unit 39 is disclosed, for example, in U.S. Patent Application Publication No. 2008/0030707. An exposure apparatus including such a measurement stage is disclosed, for example, in Japanese Laid-Open Patent Publication No. 11-135400.

The CCD imaging unit 9, together with one or both of the photodiode 16 and the CCD imaging unit 39 when necessary, may also be referred to as an information acquisition unit which acquires information related to the light intensity distribution.

In the exposure apparatus of the present embodiment, the inclination angle and inclination direction of each mirror element in the spatial light modulator, which obtains the desired light intensity distribution at the pupil position of the illumination optical system or a position

optically conjugated with the pupil position, is adjusted by the optimization calculation based on the detection results of the CCD imaging units 32 and 33. Thus, in comparison with when detecting the light intensity distribution at the pupil position of the illumination optical system and calculating the optical inclination angle and inclination direction of each mirror element SE1 in the spatial light modulator S1 based on the detection result, the inclination angle and inclination direction of each mirror element SE1 can be obtained with less calculations. This enables the desired light intensity distribution to be easily formed at the pupil position of the illumination optical system or a position optically conjugated with the pupil position. Further, the light intensity distribution at the pupil position of the illumination optical system is detected at predetermined time intervals. Based on this detection result, the optimization calculation, which is based on the detection result of the CCD imaging units 32 and 33, is corrected. This ensures accurate optimization calculations that are based on the detection result of the CCD imaging units 32 and 33. Accordingly, mask patterns may be exposed into wafers with a high resolution and satisfactory throughput.

The above-described embodiment uses a single spatial light modulator. However, a plurality of spatial light modulators may be used. A modification using a plurality of spatial light modulators will now be described with reference to Fig. 8.

Fig. 8 shows a spatial light modulation unit SM2 arranged at the position where the spatial light modulation unit SM1 shown in Fig. 1 is located, that is, in the optical

path between the beam splitter 3 and the afocal lens 5. Fig. 8 shows only the optical path between the beam splitter 3 and the afocal lens 5.

5 The spatial light modulation unit SM2 includes a divisional light guide member, which divides the incident light into two lights (generally, a plurality of lights) and then guides the first light to a first spatial light modulator S2 and the second light to a second spatial light
10 modulator S3.

 In the modification of Fig. 8, a prism P2, which is shaped as a triangular prism having a triangular cross-section along a YZ plane, is used as the divisional light
15 guide member. The prism P2 includes two side surfaces PS3 and PS4, which are symmetric to a plane lying along the optical axis and being parallel to a YZ plane. The side surface PS3 functions as a reflection surface R21 that reflects the incident light toward a plurality of mirror
20 elements in the first spatial light modulator S2. The side surface PS4 functions as a reflection surface R31 that reflects the incident light toward a plurality of mirror elements in the second spatial light modulator S3. The prism P2 divides incident light into two lights along the
25 ridgelines of the reflection surfaces R21 and R31.

 In other words, the prism P2, which functions as the divisional light guide member, includes a first deflection surface R21, which deflects the incident light toward the
30 first spatial light modulator S2, and a deflection surface R31, which deflects the incident light toward the second spatial light modulator S3. Further, the prism P2 divides the incident light into a first light and a second light

along the ridgelines of the first deflection surface R21 and the second deflection surface R31. The light that reaches the first spatial light modulator S2 is reflected by a reflection surface R22 (third deflection surface) of a planar reflection mirror PS5 and emitted out of the spatial light modulation unit SM2. The light that reaches the second spatial light modulator S3 is reflected by a reflection surface R32 (fourth deflection surface) of a planar reflection mirror PS6 and emitted out of the spatial light modulation unit SM2.

The structures of the first and second spatial light modulators S2 and S3 are the same as the spatial light modulator S1 described above and thus will not be described here.

When using the divisional light guide member P2, which divides incident light into a plurality of lights and guides the divided lights to the spatial light modulators S2 and S3, when the light entering the divisional light guide member P2 is displaced, the illuminance ratio of the light guided to the spatial light modulators S2 and S3 changes. As a result, the light intensity distribution formed at the pupil position of the illumination optical system may not be desirable. However, in this modification, the detection unit (30 to 33) detects displacement of the light entering the divisional light guide member P2 and corrects light intensity distribution errors, which are caused by the light displacement, in the light distribution shape formed at the pupil position of the illumination optical system by correcting the inclination angle and inclination direction of each mirror element in the spatial light modulators S2 and S3.

In the exposure apparatus of the above-described embodiment, a spatial light modulator that enables the orientation of two-dimensionally arranged reflection surfaces to be separately controlled is used as the spatial light modulator including a plurality of two-dimensionally arranged, separately controlled reflection elements. Examples of such a spatial light modulator are disclosed in Japanese National Phase Laid-Open Patent Publication No. 10-503300 and its corresponding European Patent Publication No. 779530, Japanese Laid-Open Patent Publication No. 2004-78136 and its corresponding U.S. Patent No. 6,900,915, Japanese National Phase Laid-Open Patent Publication No. 2006-524349 and its corresponding U.S. Patent No. 7,095,546, and Japanese Laid-Open Patent Publication No. 2006-113437. In these spatial light modulators, light that has passed through each reflection surface of the spatial light modulator enters a distribution formation optical system at a predetermined angle and forms a predetermined light intensity distribution on an illumination pupil plane in correspondence with a control signal sent to the plurality of optical elements.

Further, as the spatial light modulator, for example, a spatial light modulator enabling the height of two-dimensionally arranged reflection surfaces to be separately controlled may be used. Examples of such a spatial light modulator are disclosed in Japanese Laid-Open Patent Publication No. 6-281869 and its corresponding U.S. Patent No. 5,312,513 and Japanese National Phase Laid-Open Patent Publication No. 2004-520618 and its corresponding U.S. Patent No. 6,885,493 in Fig. 1d. In these spatial light modulators, the formation of a two-dimensional height distribution affects incident light in the same manner as a

diffraction plane.

The above-described spatial light modulator including a plurality of two-dimensionally arranged reflection surfaces may be modified in accordance with the disclosures of, for example, Japanese National Phase Laid-Open Patent Publication No. 2006-513442 and its corresponding U.S. Patent No. 6,891,655 and Japanese National Phase Laid-Open Patent Publication No. 2005-524112 and its corresponding U.S. Patent Application Publication No. 2005/0095749.

In the exposure apparatus of the above-described embodiment, an ArF excimer laser light source or a KrF excimer laser light source is used. However, an F₂ laser light source may be used instead.

In the exposure apparatus of the above-described embodiment and modification, the spatial light modulator may be controlled as described below.

A case in which the control is executed to form a specific light intensity distribution (hereafter, referred to as the first pupil intensity distribution) at the pupil position of the illumination optical system or a position optically conjugated with the pupil position will be discussed. Prior to actual exposure, the correction procedures described below are performed.

First, the first CCD imaging unit 32 and second CCD imaging unit 33, which serve as a detection unit, are used to measure the incidence angle of the light directed toward the spatial light modulator S1 (S2 and S3) and the illuminance distribution in the cross-section of the light.

Then, the detection unit sends the measurement result to the control unit 20.

Based on information of the inclination angle and inclination direction of each mirror element in the spatial light modulator S1 that is read from the storage unit 22 to generate the first pupil intensity distribution and correction information of the inclination angle and inclination direction of each mirror element SE1 that can be calculated from the measurement result of the detection unit, the control unit 20 sends a control signal to the SLM drive unit 26. The SLM drive unit 26 sets the inclination angle and inclination direction of each mirror element based on the control signal from the SLM drive unit 26.

After the setting, the CCD imaging unit 39 measures the light intensity distribution at a position conjugated with the pupil position of the projection optical system and sends the measurement results to the control unit 20. At the same time, the CCD imaging unit 9 measures the light intensity distribution formed on the incidence surface of the optical integrator 10 and sends the measurement result to the control unit 20. During the measurement, the imaging unit 39 uses as the mask M a light transmissive substrate having no pattern.

The control unit 20 compares the light intensity distribution measured by the imaging unit 39 and the first pupil intensity distribution that is to be formed. When the intensity distributions are the same (the difference therebetween being within a tolerable range), the measurement result of the CCD imaging unit 9 is stored in the storage unit 22 in association with the first pupil

intensity distribution. When the intensity distributions are not the same (the difference therebetween being outside the tolerable range), the control unit 20 performs the procedures for resetting the inclination angle and inclination direction of each mirror element S1 in the spatial light modulator S1, and the CCD imaging unit 39 repeats the measurement procedures.

In addition to the first pupil intensity distribution, when there are other types of pupil intensity distribution used for actual exposure, the correction procedures are performed for each of the pupil intensity distributions (e.g., second pupil intensity distribution and third pupil intensity distribution).

During the actual exposure, the first and second CCD imaging units 32 and 33 measure the incidence angle of the light entering the SLM and the illuminance distribution in the cross-section of the light just before exposing a single lot of wafers. Based on the measurement result, the control unit 20 sets the inclination angle and inclination direction of each mirror element SE1 in the spatial light modulator S1 with the SLM drive unit 26. In this state, the CCD imaging unit 9 measures the light intensity distribution in the cross-section of the light that enters the optical integrator 10. The measurement result is compared with the measurement result associated with the first pupil intensity distribution stored in the storage unit 22. When the measurement results are the same (the difference therebetween being within the tolerable range), exposure is actually performed. When the measurement results are not the same (the difference therebetween being outside the tolerable range), the inclination angle and inclination

direction of the mirror elements SE1 in the spatial light modulator S1 are adjusted with the SLM drive unit 26.

5 In these procedures, measurements are taken with the CCD imaging unit 9, which is always capable of performing measurements. Thus, the throughput is not decreased. When performing measurements with the CCD imaging unit 39, the CCD imaging unit 39 must be located at the light emission side of the projection optical system. Thus, during a
10 measurement, the wafer stage cannot be moved to the light emission side of the projection optical system. This decreases throughput during the measurement.

A method for manufacturing a device serving using the
15 exposure apparatus of the above-described embodiment will now be discussed with reference to the flowchart of Fig. 9. As shown in the flowchart, in a semiconductor manufacturing step, a metal film is vapor-deposited onto a wafer W, which becomes a substrate for a semiconductor device (step S40),
20 and photoresist, which is a photosensitive material, is applied to the metal film (step S42). Then, a pattern formed on a reticle (mask) is transferred onto each shot region in the wafer W with the exposure apparatus of the embodiment (step S44: exposure step). The wafer W that has undergone
25 the transfer is developed, that is, the photoresist on which the pattern has been transferred is developed (step S46: development step). Subsequently, a resist pattern formed on a surface of the wafer W is used as a mask to perform processing such as etching on the surface of the wafer W
30 (step S48: processing step).

The resist pattern is a photoresist layer including recesses and projections having shapes corresponding to the pattern transferred by the exposure apparatus of the

embodiment. The recesses extend through the photoresist layer. In step S48, the surface of the wafer W is processed through the resist pattern. The processing performed on the surface of the wafer W in step S48 includes, for example, at least either one of etching and metal film formation. In step S44, the exposure apparatus of the embodiment uses the wafer W to which photoresist is applied as a photosensitive substrate, or plate P, to transfer the pattern.

Fig. 10 is a flowchart showing the manufacturing of a liquid crystal device such as a liquid crystal display device. As shown in the flowchart, to manufacture a liquid crystal device, a pattern formation step (step S50), a color filter formation step (step S52), a cell assembly step (step S54), and a module assembly step (step S56) are sequentially performed.

In the pattern formation step of step S50, the exposure apparatus of the embodiment forms a predetermined pattern such as a circuit pattern and an electrode pattern on the plate P, which is a glass substrate to which the photoresist is applied (or the wafer W to which the photoresist is applied). The pattern formation step includes an exposure step for transferring a pattern onto a photoresist layer with the exposure apparatus of the embodiment, a development step for developing the plate P onto which the pattern has been transferred, that is, for developing the photoresist layer on the glass substrate, and a processing step for processing the surface of the glass substrate through the developed photoresist layer.

In the color filter formation step of step S52, a color filter is formed in which a plurality of sets of three

dots corresponding to R (Red), G (Green), and B (Blue) are arranged in a matrix or in which a plurality of sets of three stripe filters of R, G, and B are arranged extending in a horizontal scanning line direction.

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In the cell assembling step of step S54, a liquid crystal panel (liquid crystal cell) is assembled using the glass substrate having the predetermined pattern obtained in step S50 and the color filter obtained in step S52. More specifically, a liquid crystal panel is manufactured by injecting liquid crystal between the glass substrate and the color filter.

In a module assembling step of step S56, components such as electric circuits and a backlight for enabling a display operation of the assembled liquid crystal panel are mounted on the liquid crystal panel.

As the above-described CCD imaging unit, for example, an imaging unit with a CMOS image sensor, a photodiode array, or a camera tube may be used.

In the foregoing embodiments, it is also possible to apply a technique of filling the interior of the optical path between the projection optical system and the photosensitive substrate with a medium having the refractive index larger than 1.1 (typically, a liquid), which is so called a liquid immersion method. In this case, it is possible to adopt one of the following techniques as a technique of filling the interior of the optical path between the projection optical system and the photosensitive substrate with the liquid: the technique of locally filling the optical path with the liquid as disclosed in

International Publication WO99/49504; the technique of moving a stage holding the substrate to be exposed, in a liquid bath as disclosed in Japanese Patent Application Laid-open No. 6-124873; the technique of forming a liquid bath of a predetermined depth on a stage and holding the substrate therein as disclosed in Japanese Patent Application Laid-open No. 10-303114, and so on.

In the foregoing embodiment, it is also possible to apply the so-called polarized illumination method disclosed in U.S Pat. Published Application Nos. 2006/0203214, 2006/0170901, and 2007/0146676.

The application of the present invention is not limited to an exposure apparatus for manufacturing a semiconductor device. The present invention may also be applied to exposure apparatuses for a liquid crystal display device formed on a rectangular glass plate or for a display device such as a plasma display device. The present invention may also be widely applied to exposure apparatuses that manufacture various types of devices, such as an imaging device (CCD and the like), a micro-machine, a thin-film magnetic head, and a DNA chip. Further, the present invention may be applied to an exposure process (exposure apparatus) used when manufacturing various types of devices to form a mask (photomask, reticle, etc.) including a mask pattern during lithography.

CLAIMS

1. An illumination optical system which illuminates an irradiated plane with illumination light provided from a light source, the illumination optical system comprising:
 - a spatial light modulator which is arranged in an optical path of the illumination optical system, the spatial light modulator having a plurality of elements two-dimensionally arranged and controllable independently from each other to set traveling directions of respective light beams from the plurality of elements to predetermined traveling directions respectively;
 - a distribution forming optical system which respectively guides the respective light beams having gone through the plurality of elements of the spatial light modulator onto a pupil plane of the illumination optical system, to form a predetermined light intensity distribution onto the pupil plane;
 - a detection unit which includes a light receiving surface which receives some of the illumination light, the detection unit detecting the light intensity distribution of the illumination light at a position in an optical path extending from the light source to the spatial light modulator; and
 - a control unit which controls the traveling directions of the respective light beams from the plurality of elements based on the light intensity distribution detected by the detection unit of the spatial light modulator, to form a desirable light intensity distribution as the light intensity distribution on the pupil plane.
2. The illumination optical system according to claim 1, further comprising:

an information acquisition unit which acquires information on the light intensity distribution at a pupil position of the illumination optical system or a position optically conjugated with the pupil position; and

5 wherein the control unit corrects the controlling executed by the control unit, based on the light intensity distribution at the pupil position of the illumination optical system or the position optically conjugated with the pupil position that is acquired by the information
10 acquisition unit.

3. The illumination optical system according to claim 2, further comprising:

an optical path branching member which is arranged in
15 an optical path of the illumination optical system between the spatial light modulator and the irradiated plane, the optical path branching member branching off part of the illumination light from the optical path and guiding the branched off light to the information acquisition unit.

20 4. The illumination optical system according to claim 2, wherein the information acquisition unit acquires information on the light intensity distribution at the pupil position of the illumination optical system or the position
25 optically conjugated with the pupil position, based on the illumination light that has passed through the irradiated plane.

5. The illumination optical system according to any one
30 of claims 1 to 4, wherein:

the detection unit detects a position on the light receiving surface at which the illumination light reaches; and

the control unit controls the spatial light modulator based on the position on the light receiving surface at which the illumination light reaches.

- 5 6. The illumination optical system according to any one of claims 1 to 5, wherein:

the detection unit includes an incidence angle detection unit which detects incidence angle of the illumination light entering the spatial light modulator; and

- 10 the control unit controls the spatial light modulator based on the incidence angle detected by the incidence angle detection unit.

7. The illumination optical system according to any one
15 of claims 1 to 6, wherein:

the distribution forming optical system includes, in the order from the spatial light modulator side, an afocal optical system, an optical system for optical Fourier transmission, and an optical integrator.

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8. The illumination optical system according to any one of claims 1 to 7, wherein:

the illumination light includes a plurality of pulses,

the receiving surface of the detection unit receives

- 25 the light intensity distribution of the illumination light, formed based on one or more pulses, every one or more pulses out of the plurality of pulses, and

- the control unit controls the spatial light modulator based on a plurality of light intensity distributions of the
30 illumination light each of which is detected every one or more pulses.

9. The illumination optical system according to any one

of claims 1 to 8, wherein the spatial light modulator includes:

a first spatial light modulator which cooperates with part of the illumination optical system to form a first
5 light intensity distribution at the pupil position of the illumination optical system or the position optically conjugated with the pupil position; and

a second spatial light modulator which cooperates with part of the illumination optical system to form a second
10 light intensity distribution at the pupil position of the illumination optical system or the position optically conjugated with the pupil position.

10. The illumination optical system according to claim 9,
15 further comprising:

a divisional light guide member which is arranged in an optical path between the light source and the spatial light modulator, the divisional light guide member dividing the illumination light from the light source and guiding the
20 divided light to the first and second spatial light modulators.

11. The illumination optical system according to claim 7, wherein the detection unit detects the light intensity
25 distribution of the illumination light at a position in an optical path extending from the light source to the divisional light guide member.

12. The illumination optical system according to claim 11,
30 wherein:

each of the plurality of elements includes a reflection surface.

13. The illumination optical system according to claim 12, wherein postures of the reflection surfaces are controllable independently from each other.

5 14. An exposure apparatus which transfers a predetermined pattern onto a photosensitive substrate, the exposure apparatus comprising:

the illumination optical system according to any one of claims 1 to 13 which illuminates the pattern arranged on
10 an irradiated plane.

15. A method for manufacturing a device comprising:

an exposure step of exposing a predetermined pattern onto a photosensitive substrate using the exposure apparatus
15 according to claim 14;

a development step of developing the photosensitive substrate onto which the pattern has been transferred to form a mask layer shaped in correspondence with the pattern on a surface of the photosensitive substrate; and

20 a processing step of processing the surface of the photosensitive substrate through the mask layer.